

IPC Document Revision Table

Updated May 2011

Sorted in NUMBER order, ignore all letters

Product ID	Document Name	Responsible Committee	Status	ANSI	DoD
J-STD-001	Requirements for Soldered Electrical and Electronic Assemblies	5-22a	Rev. E 4/10 Rev D Amend 1 04/08 Rev D 2/05 Rev. C 3/00 Rev. B 10/96 Rev. A 1/95 Orig. 4/92; Supersedes IPC-S-815	4-mai	4-mai
J-STD-001xS Space Hardware Addendum	Space Applications Electronic Hardware Addendum for J-STD-001. The addendum MUST be used with the same version of the standard; e.g. 001CS with 001C, 001DS with 001D, 001ES with 001D	5-22as	ES 12/10 DS Amend 1 09/09 DS 11/06 CS 1/04		

IPC-HDBK-001	Handbook and Guide to the Requirements for Soldered Electrical and Electronic Assemblies	5-22f	Amend 2 10/05 Amend. 1 12/00 Orig. 3/98		7-jan
SMC-TR-001	An Introduction to Tape Automated Bonding Fine Pitch Technology		Orig. 1/89		
IT-WP-001	Myths of E-Commerce		Orig. 9/00		
SMC-WP-001	Soldering Capability White Paper Report		Orig. 8/91		
SMEMA 1.2	Mechanical Equipment Interface Standard		Update IPC-SMEMA-9851		
JP002	Current Tin Whiskers Theory and Mitigation Practices Guideline	5-23e	Orig. 3/06		
J-STD-002	Solderability Tests for Component Leads, Terminations, Lugs, Terminals and Wires	5-23b	Rev. C Amend. 1 10/08 Rev. C 12/07 Rev. B 2/03 Rev. A 10/98 Orig. 4/92; Supersedes IPC-S-805	10-aoû	mai-95
SMC-WP-002	An Assessment of the Use of Lead in Electronic		Orig. 8/92		

	Assembly				
J-STD-003	Solderability Tests for Printed Boards	5-23a	Rev. B 2/07 Rev. A 2/03 Original 4/92; Supersedes IPC-S-804		
SMC-WP-003	Chip Mounting		Orig. 8/93		
SMEMA 3.1	Fiducial Mark Standard				
J-STD-004	Requirements for Soldering Fluxes	5-24a	Rev. B 12/08 Rev. A 1/04 Orig. 1/95; Supersedes IPC-SF-818		mai-95
SMC-WP-004	Design for Success		Orig. 4/97		
SMEMA 4	Reflow Terms and		Orig.		
J-STD-005	Requirements for Soldering Pastes	5-24b	Amend. 1 6/96 Orig. 1/95; Supersedes IPC-SP-819		mai-95
SMC-WP-005	PWB Surface Finishes		Orig. 4/97		
IPC-HDBK-005	Guide to Solder Paste	5-24b	Orig. 1/06		
SMEMA 5	Screen Printing		Orig.		
J-STD-006	Requirements for Electronic Grade Solder Alloys and Fluxed and Non-Fluxed Solid Solders for Electronic	5-24c	Rev. B Amends 1 & 2 10/09 Rev. B Amend. 1 6/08 Rev. B 1/06		mai-95

	Soldering Applications		Rev. A 5/01 Orig. 1/95		
SMEMA 6	Electronics Cleaning		Orig.		
SMEMA 7	Fluid Dispensing		Orig.		
WP-008	Setting up Ion		Orig. 12/05		
J-STD-012	Implementation of Flip	5-21g	Orig. 1/96	Y	
J-STD-013	Implementation of Ball	5-21f	Orig. 7/96	Y	
IPC-DRM-18	Component Identification Desk Reference Manual		Rev. H 11/07 Rev. G 9/03 Rev. F 8/01 Rev. E 8/00 Rev. D 7/99 Rev. C 7/98 Rev. B 2/97 Rev. A 4/96 Orig. 9/95		
J-STD-020	Moisture/Reflow Sensitivity Classification of Plastic Surface Mount Devices	B-10a	Rev D Amend 1 3/08 Rev D 8/07 Rev. C 7/04 Rev. B 7/02 Rev. A 4/99 Orig. 10/96		
J-STD-026	Semiconductor Design	5-21g	Orig. 8/99		
J-STD-027	Mechanical Outline	5-21g	Orig. 2/03		
J-STD-028	Performance	5-21g	Orig. 8/99		

	Standard for				
J-STD-030	Guideline for Selection and	5-24f	Orig. 9/05		
J-STD-032	Performance Standard for	5-21f	Orig. 6/02		
J-STD-033	Packaging and Handling of Moisture Sensitive Non-Hermetic Solid State Surface Mount Devices	B-10a	Rev B Amend 1 1/07 Rev B 10/05 Rev. A 7/02 Orig. 4/99		
J-STD-035	Acoustic Microscopy	B-10a	Orig. 4/99		
IPC-0040	Optoelectronic Assembly	mai-25	Orig. 5/03	7-mars	
IPC-DRM-40 IPC-DRM-PTH	Through-Hole Solder Joint Evaluation Desk Reference Manual		Rev D 11/05 Renamed to DRM-PTH Rev. E 2/02 Rev. D 7/00 Rev. C 9/99 Rev. B 1/99 Rev. A 8/97 Orig. 5/97		
IPC-T-50	Terms and Definitions Interconnecting and Packaging Electronic Circuits	fév-30	Rev. H 7/08 Rev. G 12/03 Rev. F 6/96 Rev. E 7/92 Rev. D 11/88 Rev. C 3/85 Rev. B 6/80 Rev. A 8/76		

			Orig. 8/75		
IPC-DRM-53	Introduction to Electronics		Orig. 6/00		
IPC-DRM-56	Wire Preparation & Crimping		Rev A 11/06 Renamed DRM-WHA Orig. 7/02		
IPC-DRM-WHA					
IPC-SC-60	Post Solder Solvent Cleaning Handbook	5-31a	Combined to CH-65B 5/11 Rev. A 8/99 Orig. 4/87	oct-99	
IPC-SA-61	Post-Solder Semi-Aqueous Cleaning Handbook	5-31b	Combined to CH-65B 5/11 Rev. A 6/02 Orig. 7/95		
IPC-AC-62	Post Solder Aqueous Cleaning Handbook	5-31b	Combined to CH-65B 5/11 Rev. A 1/96 Orig. 12/86		
IPC-CH-65	Guidelines for Cleaning of Printed Boards and Assemblies	5-31d	Rev. B 5/11 Rev. A 9/99 Orig. 12/90	oct-99	
IPC-CS-70	Guidelines for Chemical		Orig. 8/88 Obsolete		
J-STD-075	Classification of Non-IC	B-10a	Orig. 08/08		
IPC-CM-78	Guidelines for Surface Mounting and Interconnecting Chip		Superseded by IPC-SM-780 Rev. C - 3/88		

	Carriers		Orig. 11/83		
IPC-MP-83	IPC Policy on Metrication		Orig. 8/85 Obsolete		
IPC-PC-90	General Requirements for Implementation of Statistical	juil-22	Superseded by IPC-9191 Orig. 10/90		
IPC-QS-95	General Requirements for Implementation of ISO 9000 Quality Systems	juil-22	Obsolete without replacement Orig. 4/93		
IPC-L-108	Specification for Thin Metal Clad Base Materials for Multilayer Printed Boards	3-nov	Superseded by IPC-4101 Rev. B 6/90 Rev. A 10/80 Orig. 3/76		
IPC-L-109	Specification for Resin Impregnated Fabric (Pregreg) for Multilayer Printed Boards	3-11*	Superseded by IPC-4101 Rev. B 7/92 Rev. A 10/80 Orig. 3/76		
IPC-L-110	Preimpregnated, B-Stage	3-nov	Rev. A Superseded		
IPC-CC-110	Guidelines for Selecting Core Constructions for Multilayer Printed Wiring Board Applications	3-11c	Superseded by IPC-4121 Rev. A 12/97 Orig. 1/94		
IPC-L-112	Specification for Composite Metal Clad Base materials for	3-nov	Superseded by IPC-4101 Rev. A 6/92		

	Printed Boards		Orig. 7/81		
IPC-L-115	Specification for Rigid Metal Clad Base Materials for Printed Boards	3-nov	Superseded by IPC-4101 Rev. B 4/90 Rev. A 10/80 Orig. 3/77		
IPC-L-120	Inspection Procedure for		Obsolete without		
IPC-L-125	Specifications for Plastic Substrates Clad or Unclad for High Speed/High Frequency	D-23	Superseded by IPC-4103 Rev. A 7/92 Orig. 8/83		
IPC-L-130	Specifications for Thin Laminates, Metal Clad, Primarily for General-Purpose	3-nov	Superseded by IPC-L-108 and IPC-4101 Orig. 1/77		
IPC-DD-135	Qualification Testing for		Obsolete without		
IPC-EG-140	Specification for Finished Fabric Woven from "E" Glass for Printed Boards	3-12d	Superseded by IPC-4412 Amend. 1 & 2 6/97 Orig. 3/88		
IPC-SG-141	Specification for Finished	3-12d	Orig. 2/92		
IPC-A-142	Specification for Finished	3-déc	Orig. 6/90		
IPC-QF-143	General Specification	3-12d	Orig. 2/92		
IPC-CF-148	Resin Coated Metal for Printed Boards	3-12c	Superseded by IPC-4563 Rev. A 9/98 Orig. 6/90	oct-98	

IPC-MF-150	Metal Foil for Printed Wiring Applications	3-12a	Superseded by IPC-4562 Rev. F 10/91 Changed from CF-150 to MF-150 Rev. E 5/81 Rev. D 3/76 Rev. C 8/74 Rev. B 2/71 Rev. A 9/67 Orig. 8/66		
IPC-CF-152	Composite Metallic Material Specification for Printed	3-12h	B 12/97 A 1/94 Orig. 6/90		
IPC-FC-203	Specification for Flat Cable, Round Conductor, Ground Plane	D-13	Obsolete 7/96 Orig. 7/85		
IPC-FC-210	Performance Specification for Flat-Conductor Undercarpet	D-13	Obsolete 7/96 Orig. 9/85		
IPC-FC-213	Performance Specification for Flat Undercarpet Telephone	D-13*	Obsolete 7/96 Orig. 9/84		
IPC-FC-217	General Document for Connectors, Electric, Header, Receptacle, Insulation	D-13	Obsolete 7/96 Reaffirmed 4/90 Orig. 8/82		
IPC-FC-218B/EIA-	General Specification	D-13	Obsolete 7/96		

RS-429	for Connectors, Electrical Flat Cable Type		Reaffirmed 05/91 Reaffirmed 11/81 Orig. 7/76		
IPC-FC-219	Environment Sealed Flat Cable Connectors for use in	D-13	Obsolete 7/96 Orig. 5/84		
IPC-FC-220	Specification for Flat Cable, Flat Conductor, Unshielded	D-13	Obsolete 7/96 Rev. C 7/85 Rev. B 8/75 Rev. A 1/74 Orig. 5/70		
IPC-FC-221	Specification for Flat-Copper Conductors for Flat Cables	D-13	Obsolete 7/96 Rev. A 5/84 Orig. 8/75		
IPC-FC-222	Specification of Flat Cable Round Conductor, Unshielded	D-13	Obsolete 7/96 Reaffirmed 5/91 Orig. 6/80		
IPC-FC-225	Flat Cable Design Guide		Obsolete (date) Reaffirmed 10/85 Orig. 8/75		
IPC-FC-231	Flexible Base Dielectrics for Use in Flexible Printed Wiring	D-13	Superseded by IPC-4202 Amend. 10/95 Rev. C 4/92 Rev. B 2/86		

			Rev. A 5/83 Orig. 7/74		
IPC-FC-232	Adhesive Coated Dielectric Films for Use as Cover Sheets for Flexible Printed Wiring and Flexible Bonding Films	D-13	Superseded by 4203 Amend. 10/95 Rev. C 6/94 Rev. B 2/86 Rev. A 5/83 Orig. 7/74		
IPC-FC-233	Flexible Adhesive	D-13	Incorporated into IPC-		
IPC-FC-234	PSA Assembly	D-1	Orig. 12/97		
IPC-FC-240	Single sided flex	D-12	Superseded by IPC-6013 Incorporated into FC-250 Rev. B 1/74 Rev. A 5/69 Orig. 12/65		
IPC-FC-241	Flexible Metal-Clad Dielectrics for Use in Fabrication of Flexible Printed Wiring	D-13*	Superseded by IPC-4204 Amend. 10/95 Rev. C 4/92 Rev. B 2/86 Rev. A 5/83 Orig. 7/74		
IPC-RF-245	Performance Specification for Rigid-Flex	D-12	Superseded by IPC-6013		

	Printed Boards		Orig. 4/87		
IPC-D-249	Design Standard for Flexible Single-and Double-Sided Printed	D-11	Superseded by IPC-2223 Orig. 1/87		
IPC-FC-250A	Specification for Single - and Double-Sided Flexible Printed Wiring	D-12	Superseded by IPC-6013 Rev. A 9/86 Orig. 9/86		
IPC-FA-251	Guidelines for Single and	D-12	Orig. 2/92		
IPC-D-275	Design Standard for Rigid Printed Boards and Rigid Printed Board Assemblies	D-31b	Superseded by IPC-2221 and 2222 Supersedes IPC-D-319 and IPC-D-949 Amendment 1 4/96 Orig. 9/91		
IPC-RB-276	Qualification and Performance Specification for Rigid Printed Boards	D-33a	Superseded by IPC-6011 and IPC-6012 Orig. 3/92; Supersedes IPC-SC-320B and IPC-ML-950C		
IPC-D-279	Design Guidelines for	6-10b	Orig. 7/96		
IPC-D-300	Printed Board Dimensions and Tolerances	1-10a	Superseded by IPC-2615 Rev. G 1/84		

			Rev. F 11/74 Rev. E 10/70 Rev. D 1/70 Rev. C 10/65 Rev. B 1/64 Rev. A 7/61 Orig. 8/60		
IPC-D-310	Guidelines for Phototool Generation and Measurement Techniques		Rev. C 6/91 Rev. B 12/85 Rev. A 12/77 Orig. 9/69		
IPC-A-311	Process Control		Orig. 3/96		
IPC-D-316	Design Guide for Microwave Circuit Boards Utilizing Soft Substrates	D-21b	Superseded by IPC-2252 Orig. 5/95		
IPC-D-317	Design Guidelines for Electronic Packaging Utilizing High-Speed Techniques	D-21a	Superseded by IPC-2251 Rev. A 1/95 Orig. 4/90		
IPC-HF-318	Microwave End Product Board Inspection and Test	D-22	Superseded by IPC-6018 Rev. A 12/91 Orig. 6/85		

IPC-D-319	Design Standard for Rigid Single- and Double-Sided Printed Boards	D-31b	Superseded by IPC-D-275, then by IPC-2221/2222 Orig. 1/87		
IPC-SD-320	Performance Specification for Rigid Single- and Double-Sided Printed Boards	D-33a	Superseded by IPC-RB-276 Supersedes IPC-TC-500 Rev. B 11/86 Rev. A 3/81 Orig. 1/77		
IPC-D-322	Guidelines for Selecting Printed Wiring Board Sizes Using		Reaffirmed 9/91 Orig. 8/84		
IPC-MC-324	Performance Specifications for Metal Core Boards	D-33a	Superseded by IPC-6011 and IPC-6012 Orig. 10/88		
IPC-D-325	Documentation Requirements for Printed Boards,	fév-40	Rev. A 5/95 Orig. 1/87		
IPC-D-326	Information Requirements for Manufacturing Printed	2-11a	Rev. A 1/04 Orig. 4/91		
IPC-D-330	Design Guide Manual		Orig. 1/92		
IPC-PD-335	Electronic Packaging		Orig. 12/89		
IPC-NC-349	Computer Numerical		Orig. 8/85		
IPC-D-350	Printed Board Description in	2-nov	Rev. D 7/92		

	Digital Form; Technical Content Identical to IEC-61182-1		Rev. C 10/85 Rev. B 8/77 Rev. A 2/75 Orig. 8/72		
IPC-D-351	Printed Board Drawings in		Orig. 8/85		
IPC-D-352	Electronic Design Data		Orig. 8/85		
IPC-D-354	Library Format		Orig. 2/87		
IPC-D-355	Printed Board Assembly		Orig. 1/95		
IPC-D-356	Bare Board Electrical Test Information in Digital Form	2-11c	Rev. B 10/02 Rev. A 1/98 Orig. 3/92		
IPC-AM-361	Specification for Rigid Substrates for Additive Process Printed		Superseded by IPC- 4101 Orig. 1/82		
IPC-MB-380	Guidelines for Molded		Orig. 10/90		
IPC-D-390	Automated Design Guidelines		Rev. A 2/88 Orig. 7/74		
IPC-C-406	Design and Application		Orig. 1/90		
IPC-CI-408	Design and Application		Orig. 1/94		
IPC-BP-421	General Specification for Rigid Printed Board Backplanes with Press Fit Contacts		Obsolete without replacemen t Reaffirmed 4/90 Orig. 10/80		
IPC-D-422	Design Guide for Press Fit		Orig. 9/82		
IPC-DW-	General		Orig. 1/95		

424	Specification				
IPC-DW-425	Design and End Product Requirements for Discrete Wiring Boards		Rev. A 5/90 Orig. 9/82		
IPC-DW-426	Specifications for Assembly		Orig. 12/87		
IPC-TR-460	Trouble-Shooting Checklist for Wave Soldering		Rev. A 2/84 Orig. 1973		
IPC-TR-461	Solderability Evaluation of		Orig. 3/79		
IPC-TR-462	Solderability Evaluation of		Orig. 10/87		
IPC-TR-464	Accelerated Aging for Solderability Evaluations	5-23b	Rev. A 12/87 Orig. Pub.4/84		
IPC-TR-465-1	Round Robin Test on		Orig. 1993		
IPC-TR-465-2	The Effect of Steam Aging		Orig. 1993		
IPC-TR-465-3	Evaluation of Steam Aging		Orig. 7/96		
IPC-TR-466	Wetting Balance		Orig. 4/95		
IPC-TR-467	Supporting Data and		Orig. 10/96		
IPC-TR-468	Factors Affecting		Orig. 3/79		
IPC-TR-470	Thermal Characteristic		Orig. 1/74		
IPC-TR-474	An Overview of Discrete Wiring Techniques		Obsolete without replacement Reprint 1984 Orig. 3/79		
IPC-TR-476	How to Avoid Metallic Growth Problems on Electronic Hardware		Rev. A 6/84 (new title)		

	Rev. A Electrochemical Migration Electrically Induced Failures In Printed Assemblies		Orig. 9/77		
IPC-TR-480	Results of Multilayer Test Program Round Robin IV Phase I		Obsolete without replacemen t Orig. 9/75		
IPC-TR-481	Results of Multilayer		Orig. 4/81		
IPC-TR-482	New Development		Orig. 1/76		
IPC-TR-483	Dimensional Stability Testing of Thin Laminates - Report on Phase I		Rev. A 3/91 Addendums 10/87 Orig. 4/84		
IPC-TR-484	Results of IPC Cooper Foil		Orig. 4/86		
IPC-TR-485	Results of Cooper Foil		Orig. 3/85		
IPC-TR-486	Report on Round Robin		Orig. 7/01		
IPC-TR-549	Measles in Printed		Orig. 11/78		
IPC-TR-551	Quality Assessment		Orig. 7/93		
IPC-DR-570	General Specification for 1/8 Inch Diameter Shank Carbide Drills for Printed Boards	4-déc	Obsolete without replacemen t Rev. A 4/84 Orig. 1/79		
IPC-DR-572	Drilling Guidelines for Printed Boards	4-déc	Rev A 3/07 Orig. 4/88		

IPC-TR-576	Additive Process Evaluation		Obsolete without replacement Orig. 9/77		
IPC-TR-578	Leading Edge Manufacturin		Orig. 9/84		
IPC-TR-579	Round Robin Reliability		Orig. 9/88		
IPC-TR-580	Cleaning and Cleanliness		Orig. 10/89		
IPC-TR-581	IPC Phase 3 Controlled		Orig. 8/94		
IPC-TR-582	IPC Phase 3 No-Clean Flux		Orig. 11/94		
IPC-TR-583	An In-Depth Look At Ionic		Orig. 7/02		
IPC-WP/TR-584	IPC White Paper and Technical Report on Halogen-Free	avr-33	Rev A 8-07 Orig. 4/03		
IPC-TR-585	Time, Temperature		Orig. 5/06		
IPC-TR-586	Immersion Silver Plating	avr-14	Orig. 5/09		
IPC-A-600	Acceptability of Printed Boards	7-31a & D-33a	Rev. H 4/10 Amend. 1 01/08 Rev. G 7/04 Rev. F 11/99 Rev. E 8/95 Rev. D '89 Rev. C '78 Rev. B '74 Rev. A '70 Orig. '64		
IPC-SS-605	Printed Board Quality		Obsolete without		
IPC-QE-605	Printed Board Quality		Rev. A 2/99		
J-STD-609	Marking and Labeling of	4-34b	Rev. A 2/10	7-aoû	1-aoû

	Components, PCBs and PCBAs to Identify Lead (Pb) Pb-Free and Other		Orig. 5/07; Supersedes IPC-1066		
IPC-A-610	Acceptability of Electronic Assemblies	juil-31	Rev E 4/10 Rev D Amend 1 4/08 Rev. D 2/05 Rev. C 1/00 Rev. B 12/94 Rev. A 3/90 Orig. 8/83	4-mai	4-mai
IPC-A-610DC	IPC-A-610D Telecom		Orig. 8/09		
IPC-HDBK-610	Handbook and Guide to IPC-A-610 (Includes B-C-D)		Amend 1 10/05 Orig. 9/02		
IPC-QE-615	Assembly Quality		Obsolete without		
IPC/WHMA-A-620	Acceptability of Electronic Wire Harnesses and Cables	7-31f	Rev A 7/06 Orig. 1/02	3-fév	
IPC/WHMA-A-620xS	Space Applications	7-31fs	AS 1/11		
IPC-AI-640	User's Guidelines for Automated Inspection of Unpopulated Thick Film Hybrid		Obsolete without replacement Orig. 1/87		
IPC-AI-641	User's Guidelines for Automated Solder Joint Inspection		Obsolete without replacement Orig. 1/87		

IPC-AI-642	User's Guidelines for Automated Inspection of Artwork, Interlayers, and		Obsolete without replacement Orig. 10/88		
IPC-OI-645	Standard for Visual Optical		Orig. 10/93		
IPC-TM-650	Test Methods Manual		Updated per test		
IPC-ET-652	Guidelines and Requirements for Electrical Testing of Unpopulated		Superseded by IPC-9252 Orig. 10/90		
IPC-QL-653	Qualification of Facilities that Inspect/Test Printed		Rev. A 11/97 Orig. 8/88		
IPC-MI-660	Incoming Inspection of		Orig. 2/84		
IPC-R-700	Suggested Guidelines for Modification, Rework and Repair of Printed Boards and Assemblies		Superseded by IPC-7711A/7721A Rev. C 1/88 Rev. B 9/77 Rev. A 12/71 Orig. 9/67		
IPC-TA-720	Technology Assessment		Orig. '86		
IPC-TA-721	Technology Assessment		Orig. '88		
IPC-TA-722	Technology Assessment		Orig. '90		
IPC-TA-723	Technology Assessment		Orig. '91		
IPC-TA-724	Technology Assessment		Orig. 4/98		
IPC-PE-740	Troubleshooting Guide for Printed Board Manufacture and Assembly	juil-23	Rev. A 12/97 Orig. 1/85		

IPC-CM-770	Printed Board Component Mounting		Rev. E 1/04 Rev. D 1/96 Rev. C 1/87 Rev. B 10/80 Rev. A 3/76 Orig. 9/68		
IPC-SM-780	Component Packaging		Orig. 3/88		
IPC-SM-782	Surface Mount Design and Land Pattern Standard	jan-13	Superseded by IPC-7351 Amend. 2 4/99 Amend. 1 10/96 Rev. A 8/93 Orig. 3/87		
IPC-SM-784	Guidelines for Chip-on-		Orig. 11/90		
IPC-SM-785	Guidelines for Accelerated		Orig. 11/92		
IPC-SM-786	Procedures for Characterizing and Handling of Moisture/Reflow Sensitive ICs		Superseded by J-STD-020 and J-STD-033 Rev. A 1/95 Orig. 12/90		
IPC-MC-790	Guidelines for Multichip		Orig. 8/92		
IPC-S-801		5-23a	Superseded by IPC-804		
IPC-S-803		5-23a	Superseded by IPC-804		
IPC-S-804	Solderability Test Methods for Printed Wiring Boards	5-23a	Superseded by J-STD-003 Rev. A 1/87		

			Orig. 1/82		
IPC-S-805	Solderability Tests for Component Leads and Terminations	5-23b	Superseded by J-STD-002 Orig. 1/85		
IPC-MS-810	Guidelines for High Volume		Orig. 10/93		
IPC-S-815	General Requirements for Soldering Electronic Interconnections		Superseded by J-STD-001 Rev. B 12/87 Rev. A 6/81 Orig. 11/77		
IPC-S-816	SMT Process Guideline and		Orig. 7/93		
IPC-SM-817	General Requirements		Orig. 11/89		
IPC-SF-818	General Requirement for Electronic Soldering Fluxes	5-24a	Superseded by J-STD-004 Rev. 12/91 Orig. 2/88		
IPC-SP-819	General Requirements and Test Methods for Electronic Grade Solder	5-24b	Superseded by J-STD-005 Orig. 10/88		
IPC-AJ-820	Assembly and Joining		Orig. 8/96		
IPC-CA-821	General Requirements		Orig. 1/95		
IPC-CC-830	Qualification and Performance of Electronic Insulating Compound for Printed Board		Amend. 1 10/08 Rev B 08/02 Amend. 1 7/99 Rev. A 10/98	8-fév	

	Assemblies		Orig. 1/84		
IPC-HDBK-830	Conformal Coating		Orig. 10/02		
IPC-SM-839	Pre and Post Solder Mask		Orig. 4/90		
IPC-SM-840	Qualification and Performance of Permanent Polymer Coating (Solder Mask) for Printed Boards	5-33b	Rev. E 12/10 Rev. D 4/07 Amend. 1 6/00 Rev. C 1/96 Rev. B 5/88 Rev. A 7/83 Orig. 11/77	8/00	
IPC-HDBK-840	Solder Mask Handbook		Orig. 09/06		
IPC-H-855	Hybrid Microcircuit Design Guide		Obsolete without replacement Orig. 10/82		
IPC-D-859	Design Standard for		Orig. 12/89	Y	
IPC-HM-860	Specification for Multilayer		Orig. 1/87	Y	
IPC-TF-870	Qualification and		Orig. 11/89	Y	

IPC-ML-910	Design and End Production Specification for Rigid Multilayer Printed Boards	D-31b & D-33a	Superseded by IPC-D-949, IPC-D-275, and subsequently IPC-2221 for Design and IPC-ML-950, IPC-RB-276, and subsequently IIPC-6011 for End Product Specification Rev. A 8/76 Orig. 6/68		
IPC-D-949	Design Standard for Rigid Multilayer Printed Boards	D-31b	Superseded by IPC-D-275 and subsequently by IPC-2221/2222 Orig. 1/87		
IPC-ML-950	Performance Specification for Rigid Multilayer Printed Boards	D-33a	Superseded by IPC-RB-276 and subsequently IPC-6011/6012 Rev. C 11/8 Rev. B 12/77 Rev. A 9/70 Orig. 1/66		

IPC-ML-960	Qualification and		Orig. 7/94	Y	
IPC-ML-975	End Product Documentation Specification for Multilayer Printed		Superseded by IPC-D-325 Orig. 9/69		
IPC-ML-990	Performance Specification for Flexible Multilayer Wiring	D-33a	Superseded by IPC-6011 Orig. 9/72		
IPC-1043	Cleaning & Cleanliness		Orig. 8/92		
IPC-1044	Cleaning & Cleanliness		Orig. 10/92		
IPC-1065	Material Declaration	4-34a	Orig. 1/05		
IPC-1066	Labeling of PCBs and Assemblies	4-34b	Superseded by J-STD-609 Orig. 12/04		
IPC-1071	Best Industry Practices for	E-20	Orig. 1/11		
IPC-TP-1090	The Layman's Guide to		Orig. 7/96		
IPC-TP-1103	Manufacturing Concerns		Obsolete without		
IPC-TP-1114	The Layman's Guide to		Orig. 1/98		
IPC-TP-1115	Selection and Implementation		Orig. 12/98		
IPC-1131	IT Guidelines for PWB		Orig. 4/00		
IPC-1331	Voluntary Safety		Orig. 3/00		
IPC-1601	Printed Board Handling and	D-35	Orig. 8/10		
IPC-1710	OEM Standard for Printed Board Manufacturers' Qualification Profile (MQP)		Rev. A 7/04 12/97 updated Orig. 2/94		
IPC-1720	Assembly Qualification		Rev. A 7/04		

	Profile (AQP)		Orig. 7/96		
IPC-1730	Laminator Qualification Profile (LQP)		Rev. A 6/00 Orig. 1/98		
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IPC-1752	Materials Declaration Management (Includes 2 PDF forms)	2-18b	Rev. A 2/10 Vers. 1.1 3/07 Orig. Pub. 3/06		
IPC-1756	Manufacturing Process	2-18a	Orig. 4/10		
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IPC-2152	Standard for Determining	1-10b	Orig. 8/09		
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IPC-2222	Sectional Design Standard for Rigid Organic Printed Boards	D-31b	Rev. A 12/10 Orig. 2/98; Supersedes IPC-D-275		

IPC-2223	Sectional Design Standard for Flexible Printed Boards	D-11	Rev. B 5/08 Rev. A 6/04 Orig. 11/98; Supersedes IPC-D-249		
IPC-2224	Sectional Standard for		Orig. 1/98		
IPC-2225	Sectional Design		Orig. 5/98		
IPC-2226	Design Standard for	1-oct	Orig. 4/03		
IPC-2251	Design Guidelines for	D-21a	Orig. 12/03		8-sep
IPC-2252	Design and Manufacturin	D-21b	Orig. 7/02		
IPC/JPCA-2315	Design Guide for High	D-41a	Orig. 6/00		
IPC-2316	Design Guide for Embedded	D-37a	Orig. 3/07		
IPC-2501	Definition for Web-based	fév-50	Orig. 7/03	8-mars	
IPC-2511	Generic Requirements for Implementation of Product Manufacturing Description	2-nov	Rev. B 1/02 Rev A 1/00 Orig. 11/98	2-fév	
IPC-2512	Sectional Requirements for Implementation of	2-nov	Rev A 11/00 Orig. 11/98		
IPC-2513	Sectional Requirements	2-11h	Rev A 11/00		
IPC-2514	Sectional Requirements	2-nov	Rev A 11/00		
IPC-2515	Sectional Requirements	2-nov	Rev A 11/00		
IPC-2516	Sectional Requirements	2-11e	Rev A 11/00		
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IPC-2518	Sectional Requirements	2-nov	Rev A 11/00		
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IPC-2531	Standard	2-déc	Orig. 3/99		

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IPC-2541	Generic Requirements	2-13a	Orig. 10/01	Y	
IPC-2546	Sectional Requirements for Shop Floor Electronic Assembly Equipment	2-13b	Amend. 1 01/03 Amend. 2 01/05 Orig. 10/01	Y	
IPC-2547	Sectional Requirements	2-13c	1-fév	Y	
IPC-2571	Generic Requirements	2-15a	11-jan	Y	
IPC-2576	Sectional Requirements	2-15c	11-jan	Y	
IPC-2578	Sectional Requirements	2-15e	11-jan	Y	
IPC-2581	Generic Requirements for Printed Board Assembly	fév-17	Amend 1 5/07 Orig. 3/04	5-avr	
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IPC-2612-1	Sectional Requirements	fév-40	Orig. 4/10		
IPC-2614	Sectional Requirements	fév-40	Orig. 4/10		
IPC-2615	Printed Board Dimensions		Orig. 6/00; Supersedes Orig. 7/96	Y	
IPC-3406	Guidelines for Electrically		Orig. 11/96		
IPC-3408	General Requirements		Orig. 11/96		
IPC-4101	Specification for Base Materials for Rigid and Multilayer Boards	3-nov	Rev. C 8/09 Rev. B Amends 1&2 4/07 Rev. B Amend 1 2/07		

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IPC/JPCA-4104	Specification for High	3-oct	Orig. 5/99	mai-99	
IPC-4110	Specification and	3-12*	Orig. 8/98	oct-98	
IPC-4121	Guidelines for Selecting	3-11c	Orig. 1/00; Supersedes		
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IPC-4552	Specification for	avr-14	Orig. 10/02	11-fév	
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IPC-4562	Metal Foil for Printed Wiring Applications	3-12a	Rev. A 4/08 Amend. 1 5/05 Orig. 5/00; Supersedes IPC-MF- 150F		2-mars
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IPC-4761	Design Guide for Protection		Orig. 7/06		
IPC-4781	Qualification and	5-33e	Orig. 5/08		
IPC-4811	Specification for Embedded	D-52	Orig. 4/08		
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IPC-7095	Design and Assembly Process Implementation for BGAs	5-21f	Rev. B 3/08 Rev. A 11/04 Orig. 8/00	7-aoû	
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IPC-7525	Guidelines for Stencil Design	7-21e	Rev. A 2/07 Orig. 5/00	06/00	
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IPC-7711/7721	Rev B renamed to: Rework, Repair and Modification of Electronic Assemblies	5-31h	Rev B 11/07 Rev A 10/03 Orig. 4/98; Supersedes IPC-R-700C		
IPC-7912	Calculation of DPMO and Manufacturing Indices for Printed	5-22g	Rev. A 1/04 Orig. 7/00	1-avr	
IPC-8413-1	Specification for	5-25a	Orig. 4/03		
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IPC-9151	Printed Board Capability, Quality and Relative Reliability (PCQR2) Benchmark Test Standard and Database	D-36	Rev. C 5/10 Rev. B 2/07 Rev. A 5/03 Orig. 6/02		
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IPC-9194	Implementation of	juil-22	Orig. 9/04		
IPC-9199	SPC Quality Rating	juil-22	Orig. 9/02		
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IPC-9252	Guidelines and Requirements for Electrical Testing of Unpopulated Printed Boards	7-32c	Rev. A 11/08 Orig. 02/01; Supersedes IPC-ET-652A		4-sep
IPC-9261	In-Process DPMO and Estimated Yield for PWAs	5-22g	Rev. A 10/06 Orig. 3/02	3-fév	
IPC-9501	PWB Assembly	5-21c	Orig. 7/95		
IPC-9502	PWB Assembly		Orig. 4/99		
IPC-9503	Moisture Sensitivity Classification for Non-IC Components		Superseded by J-STD-075 08/08 Orig. 4/99		
IPC-9504	Assembly Process		Orig. 6/98	oct-98	
IPC-9591	Performance	sep-81	Orig. 4/06		

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IPC-9592	Requirements for Power Conversion Devices for the Computer	sep-82	Rev. A 5/10 Orig. 9/08		
IPC-9631	User Guide for IPC-TM-	D-32	Orig. 12/10		
IPC-9691	User Guide for the IPC-TM-650, Method 2.6.25,	5-32e	Rev A 8/07 Orig. 10/05		
IPC-9701	Qualification and Performance Test Methods for Surface	6-10d	Rev. A 2/06 Orig. 1/02	Y	
IPC/JEDEC-9702	Monotonic Bend	6-10d	Orig. 6/04		
IPC/JEDEC-9703	Mechanical Shock Test	6-10d	Orig. 3/09		
IPC/JEDEC-9704	Printed Wiring Board	6-10d	Orig. 6/05		
IPC-9708	Test Methods for	6-10d	Orig. 12/10		
IPC-9850	Surface Mount		Orig. 7/02	9-fév	
IPC-SMEMA-9851	Equipment Interface		Orig. 11/04		
IPC-DRM-SMT	Surface Mount Solder Joint Evaluation Desk Reference Manual		Rev. C 11/05 Rev. B 4/00 Rev. A 3/99 Orig. 7/98		
IPC-EMSI-TC	IPC Sample Master		Orig. 3/02		
Roadmap	International Technology Roadmap for Electronic Interconnections	aoû-40	Updated 2009 Updated 2007 Updated 2005 Updated 2003 Updated 2001 Updated 9/97		

```
var gaJsHost = (("https:" == document.location.protocol) ? "https://ssl." : "http://www
```



```
v."); document.write(unescape("%3Cscript src=" + gaJsHost + "google-analytics.com/g
```



```
ja.js' type='text/javascript'%3E%3C/script%3E"); try { var pageTracker = _gat._getTra
```



```
acker("UA-8373432-1"); pageTracker._trackPageview(); } catch(err) {}
```